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New generations of RF Amplifiers: from system requirements to technologies

Michel Caplot, Christian Robert, Michel Grezaud, Bernard Darges and Pascal Ponard cw RF Workshop – CERN – March 2008

Components & Subsystems

From System requirements to Technologies....and not the opposite way

System requirements do include technical performance but are not limited to these performance

Systems requirements should cover system life time

Cost of a system is not limited to purchasing cost: it clearly include Life Cycle Costs (LCC)

- Purchasing cost
- Maintenance cost
- System evolution cost
- Supplier support cost
- Spare part cost

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1 Components & Subsystems



System requirements (2) 🗲

Systems Requirements

- Technical performance
- LCC including availability of spare parts over 2 or 3 decades
- System architecture
- System reliability
- System availability (fault tolerance, graceful degradation, maintainability, testability, ...)



Architectures (1) 📀



Large klystron based RF amplifiers



High power Few items to maintain Centralized architecture

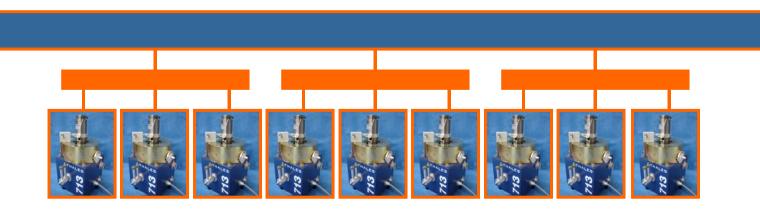


Multi-IOT based RF amplifiers

Lower power at each stage Easy replacement Decentralized architecture with local control

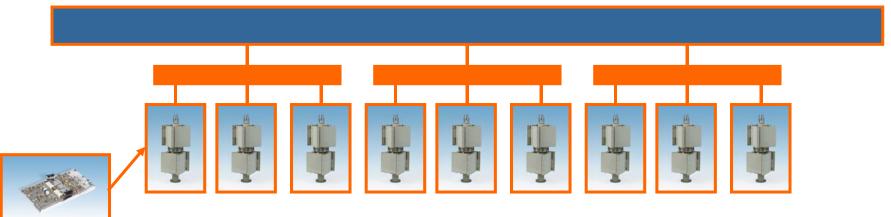






Multi-coupled IOT based RF amplifiers

Coupling losses Graceful degradation Easy replacement



Multi-coupled Solid State based RF amplifiers

Coupling losses Low voltage Obsolescence management





Architecture should not take into account technologies

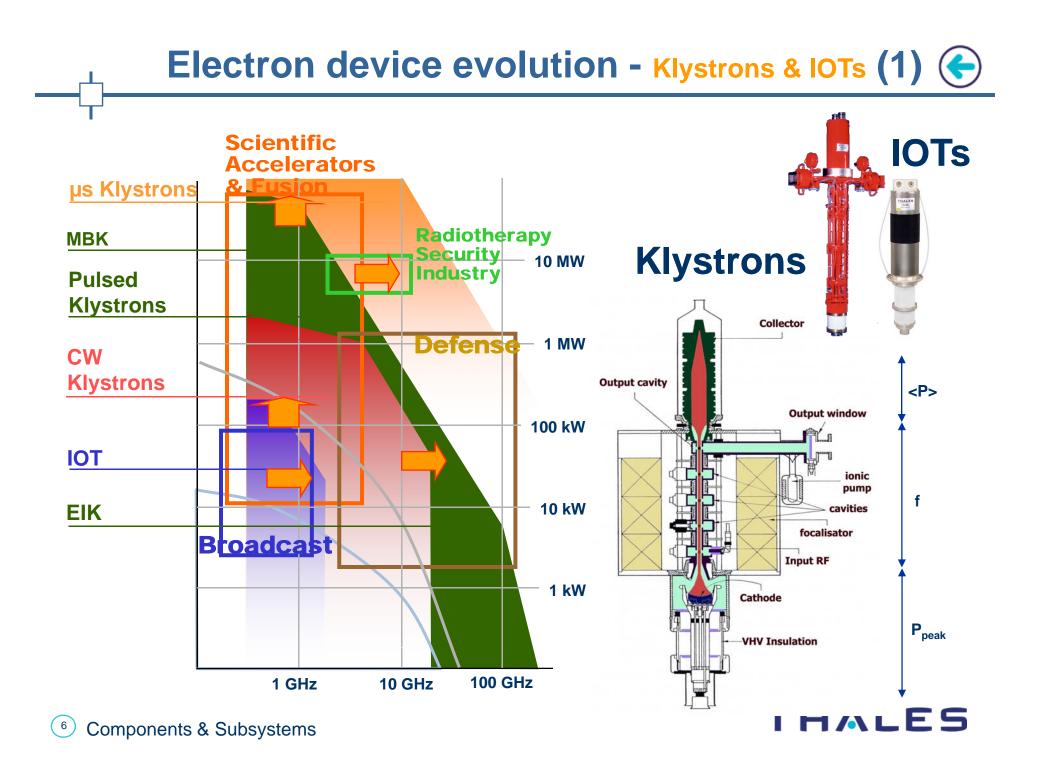
- Architecture is strongly dependent on requirements
- ✓ Solid State vs. Electron Device architectures : really a debate ?

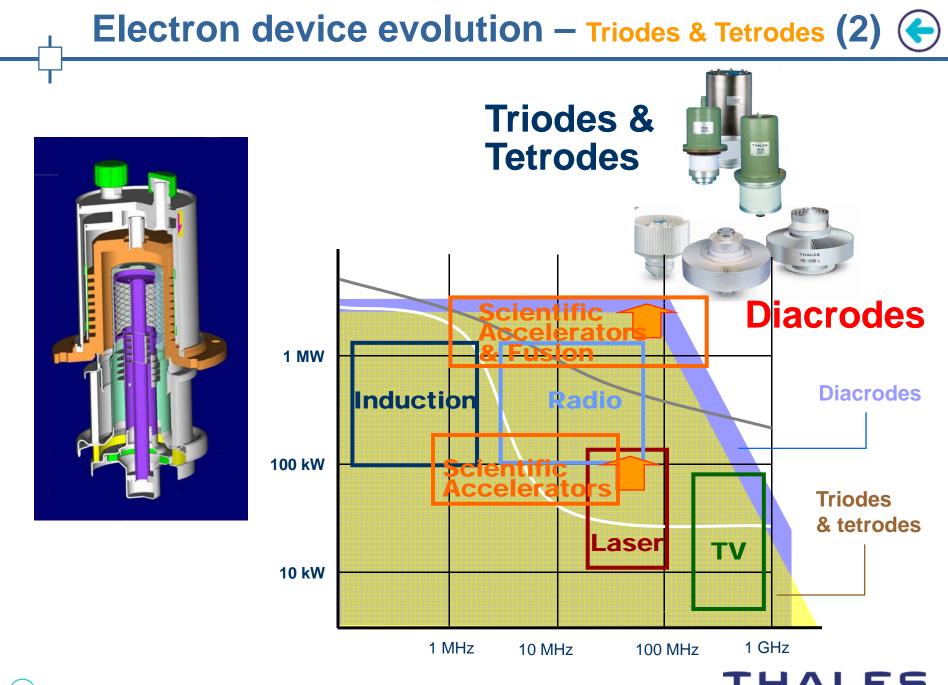
Solid State	Electron Devices
Low voltage	High voltage
Graceful degradation but coupling losses	Some possible graceful degradation
Obsolescence management	Few suppliers but existing (!!!)
Components not driven by science market	Ability to produce components some decades after system start
LCC (design evolution due to new components)	LCC

In both cases, experienced high power RF designers are mandatory !!!





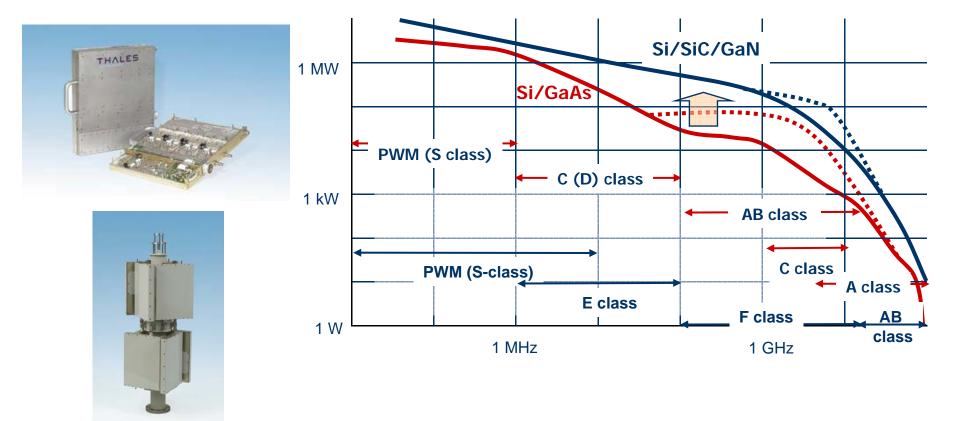




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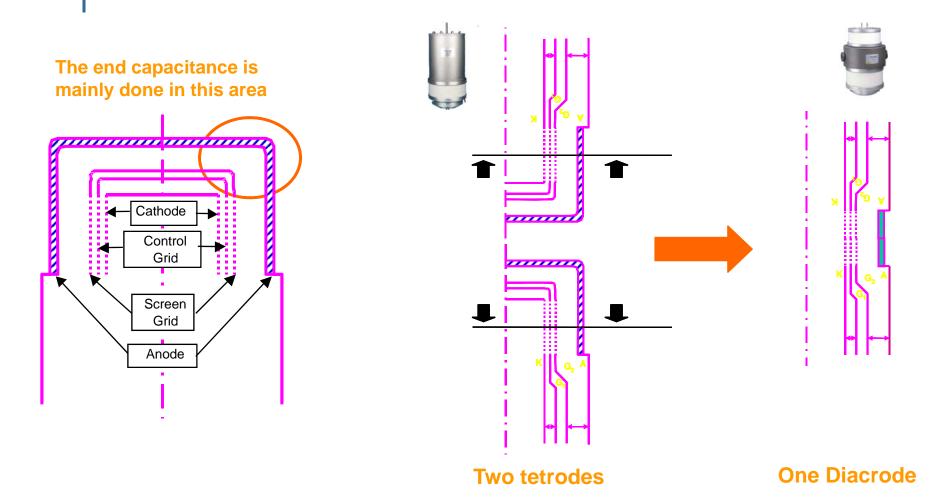
Electron device evolution – Solid State Device (3)

Solid State amplifiers



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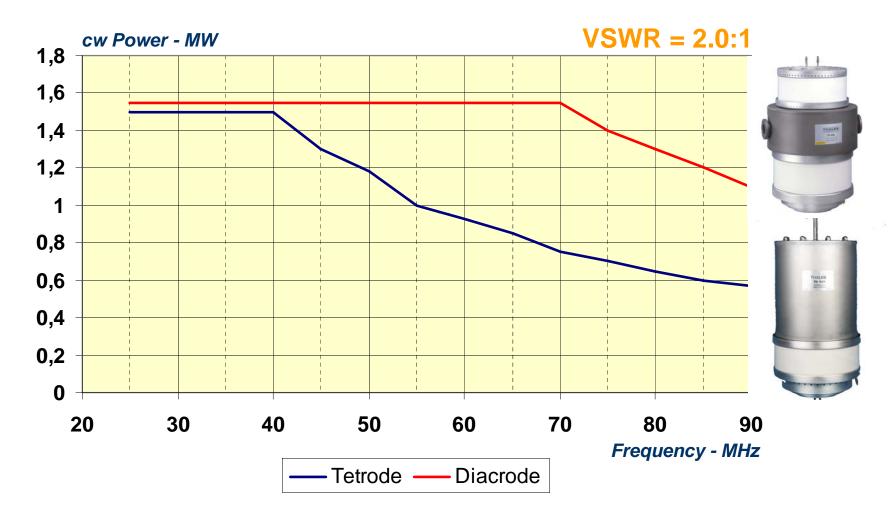
Diacrode - A major evolution for tetrode technology (1) (







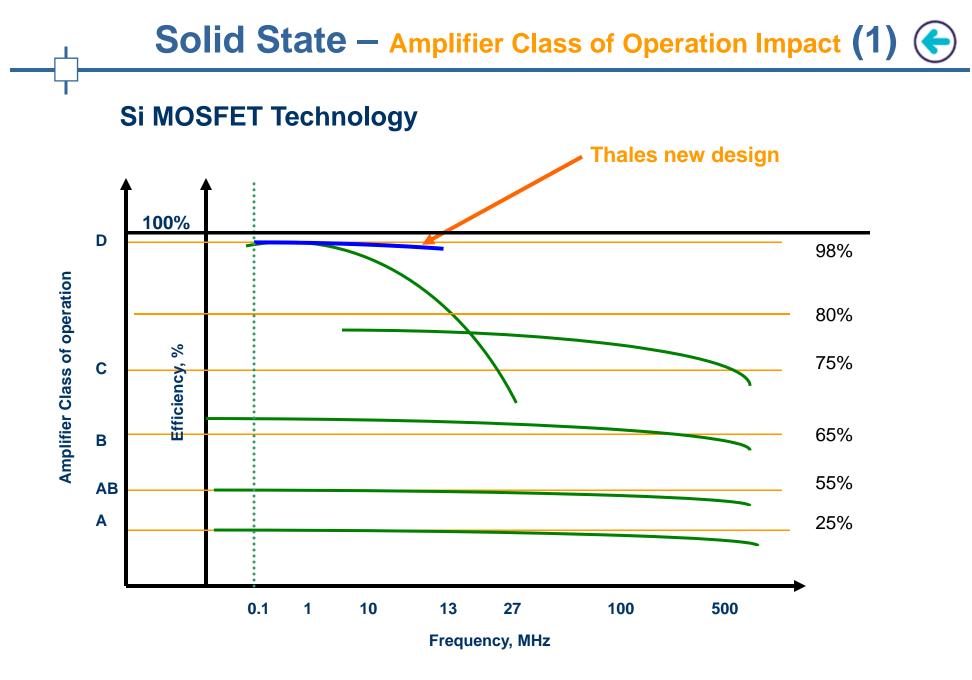
Diacrode - A major evolution for tetrode technology (2) (<



Both tubes with the same cathode





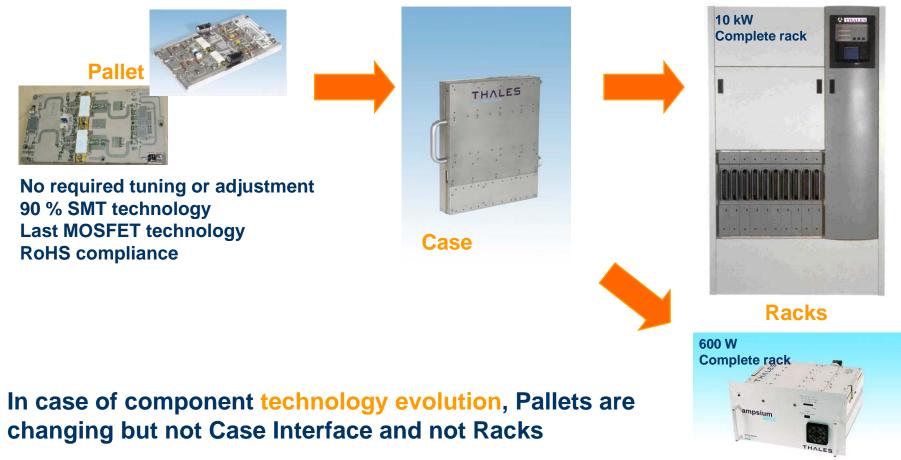


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Solid State – Amplifier structure Impact (2)

Si LDMOS Technology (low frequency)



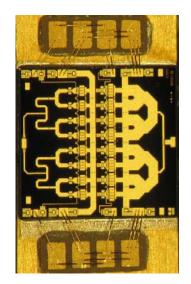




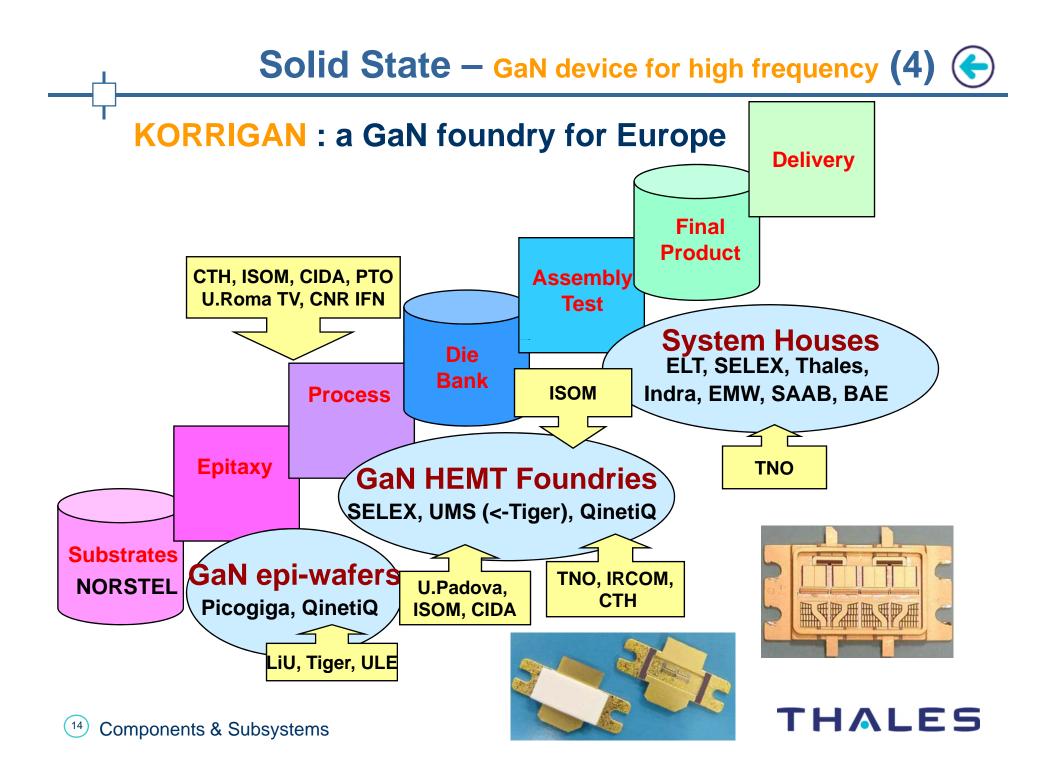
KORRIGAN : a GaN foundry for Europe

GaN TECHNOLOGY

RF power density x 10
Output power x 10
Power added efficiency x 2
Junction temperature > 250°C
Voltage supply > 28V







IOTs – Modularity based design (1) 📀



Diamond TH793 IOTs 450-850 MHz 80 kW cw

¹⁵ Components & Subsystems

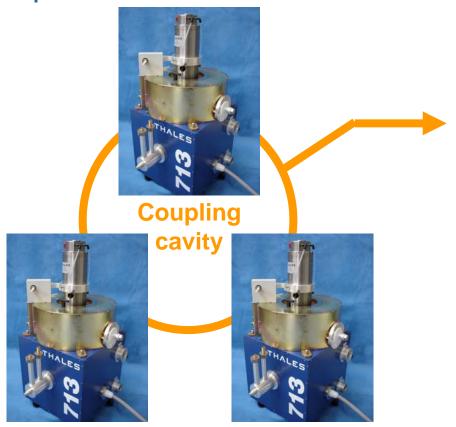




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TH713 IOTs L band 16 kW cw





Combined RF Output

Modularity allows for Fault tolerance through graceful degradation, due to the operation of each RF source at a lower power: in case of one source failure, two remaining can supply full power





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New generations of RF amplifiers should be defined by System Requirements that include technical performance but also system operation requirements and Life Cycle Costs (and not only Purchasing Cost)

FFR

There is not a debate between Solid State and Electron devices: based on system requirements, technological answers may be based on a unique type or on a combination of technologies

Both Solid State and Electron devices have evolutions. SSD design based amplifier must incorporate an architecture that allows to mix different solid state technologies in order to take into account that science is not the market driver

